

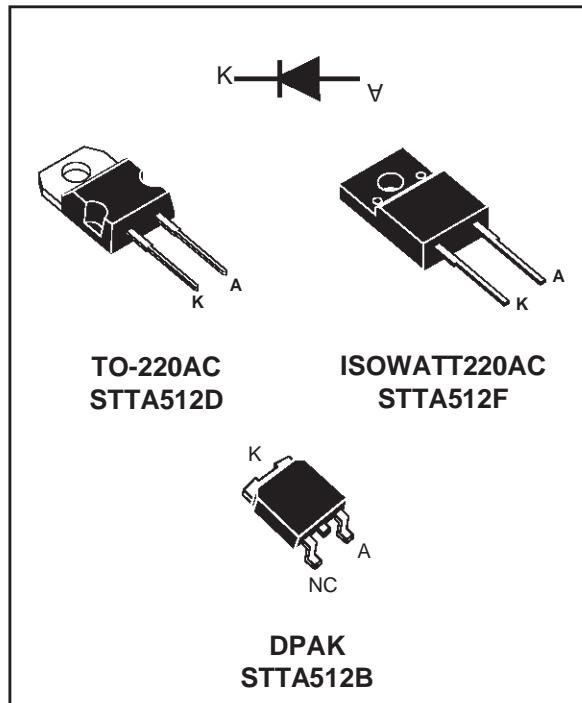
## TURBOSWITCH™ "A". ULTRA-FAST HIGH VOLTAGE DIODE

### MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	5A
$V_{RRM}$	1200V
$t_{rr}$ (typ)	45ns
$V_F$ (max)	2.0V

### FEATURES AND BENEFITS

- SPECIFIC TO THE FOLLOWING OPERATIONS: SNUBBING OR CLAMPING, DEMAGNETIZATION AND RECTIFICATION
- ULTRA-FAST, SOFT AND NOISE-FREE RECOVERY.
- VERY LOW OVERALL POWER LOSSES IN BOTH THE DIODE AND THE COMPANION TRANSISTOR.
- HIGH FREQUENCY AND/OR HIGH PULSED CURRENT OPERATIONS.
- CECC APPROVED.



### DESCRIPTION

TURBOSWITCH 1200V drastically cuts losses in all high voltage operations which require extremely fast, soft and noise-free power diodes. Due to their optimized switching performances they also highly decrease power losses in any associated switching IGBT or MOSFET in all "Freewheel Mode" operations.

They are particularly suitable in Motor Control circuitries, or in the primary of SMPS as snubber, clamping or demagnetizing diodes, and also at the secondary of SMPS as high voltage rectifier diodes.

### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		1200	V
$V_{RSM}$	Non repetitive peak reverse voltage		1200	V
$I_{F(RMS)}$	RMS forward current		20	A
$I_{FRM}$	Repetitive peak forward current	$tp = 5 \mu s$ $F = 5\text{kHz}$	75	A
$I_{FSM}$	Surge non repetitive forward current	$tp = 10\text{ms Sine}$	45	A
$T_j$	Maximum operating junction temperature		150	°C
$T_{stg}$	Storage temperature		-65 to 150	°C

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## STTA512D/F/B

### THERMAL AND POWER DATA

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-c)}$	Junction to case thermal resistance	STTA512D/B STTA512F	4.0 5.5	°C/W
$P_1$	Conduction power dissipation (see fig. 6)	$I_F(AV) = 5A \quad \delta = 0.5$ STTA512D/B $T_c = 102^\circ C$ STTA512F $T_c = 84^\circ C$	12	W
$P_{max}$	Total power dissipation $P_{max} = P_1 + P_3 \quad (P_3 = 10\% P_1)$	STTA512D/B $T_c = 98^\circ C$ STTA512F $T_c = 78^\circ C$	13	W

### STATIC ELECTRICAL CHARACTERISTICS (see figure 6)

Symbol	Parameter	Test Conditions		Min	Typ	Max	Unit
$V_F$ *	Forward voltage drop	$I_F = 5A$	$T_j = 25^\circ C$ $T_j = 125^\circ C$		1.35	2.2 2.0	V V
$I_R$ **	Reverse leakage current	$V_R = 0.8 \times V_{RRM}$	$T_j = 25^\circ C$ $T_j = 125^\circ C$		0.3	100 2.0	$\mu A$ mA
V <sub>to</sub>			$T_j = 125^\circ C$			1.57	V
R <sub>d</sub>	Dynamic resistance					0.086	mΩ

Test pulses widths : \*  $t_p = 380 \mu s, \delta < 2\%$

\*\*  $t_p = 5 ms, \delta < 2\%$

### DYNAMIC ELECTRICAL CHARACTERISTICS

#### TURN-OFF SWITCHING (see figure 7)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t <sub>rr</sub>	Reverse recovery time	$T_j = 25^\circ C$ $I_F = 0.5 A \quad I_R = 1A \quad I_{rr} = 0.25A$ $I_F = 1 A \quad dI_F/dt = -50A/\mu s \quad V_R = 30V$		45	95	ns
I <sub>RM</sub>	Maximum reverse recovery current	$T_j = 125^\circ C \quad V_R = 600V \quad I_F = 5A$ $dI_F/dt = -40 A/\mu s$ $dI_F/dt = -500 A/\mu s$		20	7.5	A
S factor	Softness factor	$T_j = 125^\circ C \quad V_R = 600V \quad I_F = 5A$ $dI_F/dt = -500 A/\mu s$		1.2		/

#### TURN-ON SWITCHING (see figure 8)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
t <sub>fr</sub>	Forward recovery time	$T_j = 25^\circ C$ $I_F = 5 A, dI_F/dt = 40 A/\mu s$ measured at $1.1 \times V_{Fmax}$			900	ns
V <sub>Fp</sub>	Peak forward voltage	$T_j = 25^\circ C$ $I_F = 5A, dI_F/dt = 40 A/\mu s$ $I_F = 40A, dI_F/dt = 500 A/\mu s$		50	35	V

**APPLICATION DATA**

The 1200V TURBOSWITCH series has been designed to provide the lowest overall power losses in all high frequency or high pulsed current operations. In such applications (Fig 1 to 5), the way of calculating the power losses is given below:

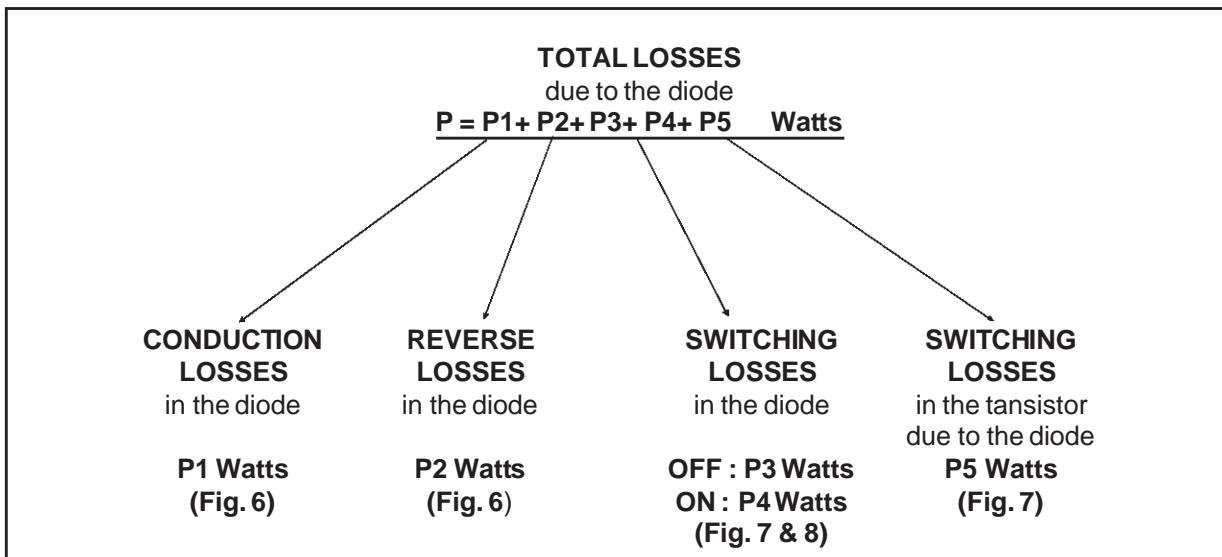
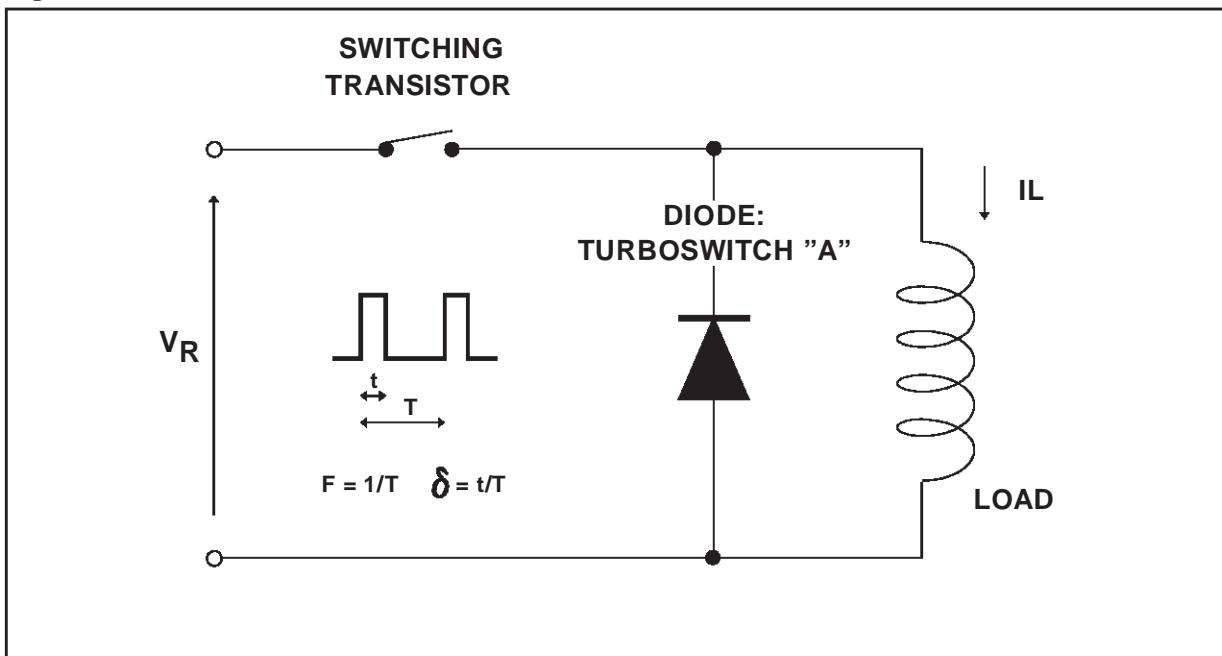
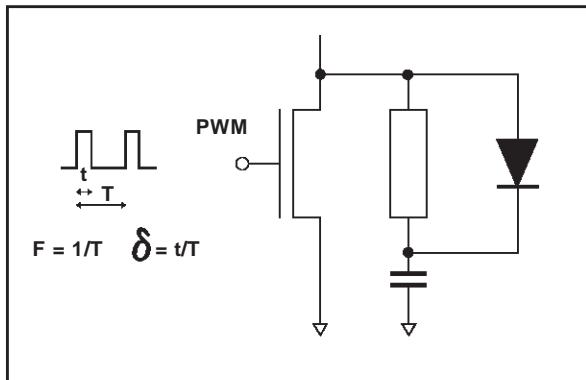


Fig. 1 : "FREEWHEEL" MODE.

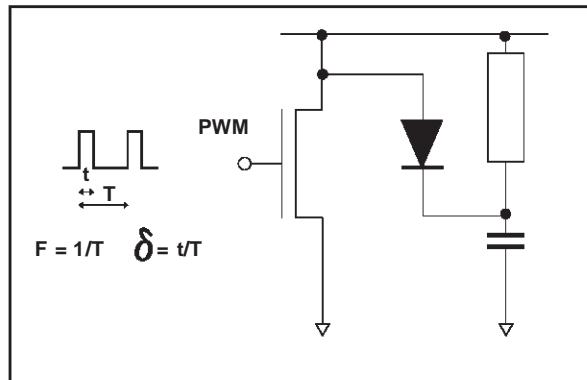


## STTA512D/F/B

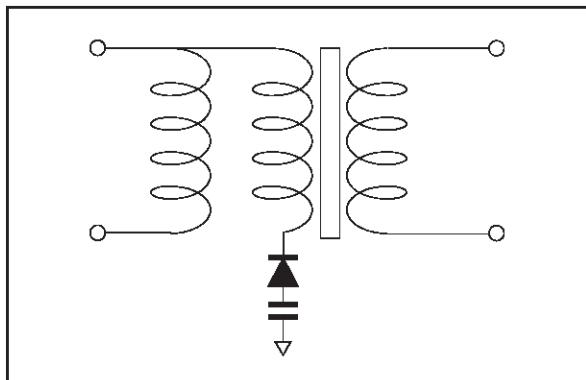
**Fig. 2 : SNUBBER DIODE.**



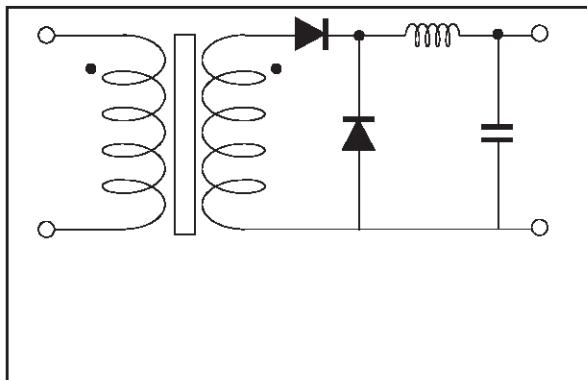
**Fig. 3 : CLAMPING DIODE.**



**Fig. 4 : DEMAGNETIZING DIODE.**

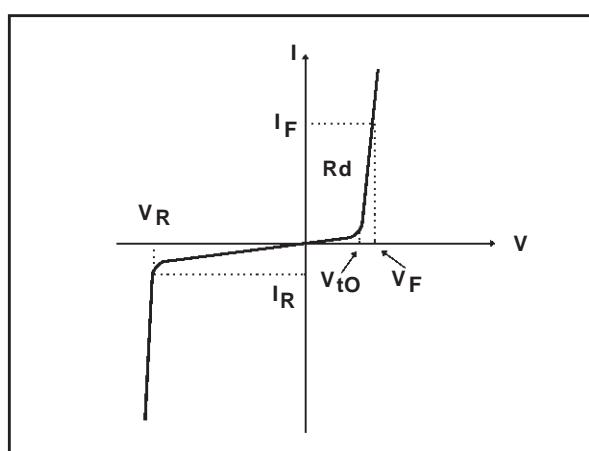


**Fig. 5 : RECTIFIER DIODE.**



## STATIC & DYNAMIC CHARACTERISTICS . POWER LOSSES .

**Fig. 6: STATIC CHARACTERISTICS**



**Conduction losses :**

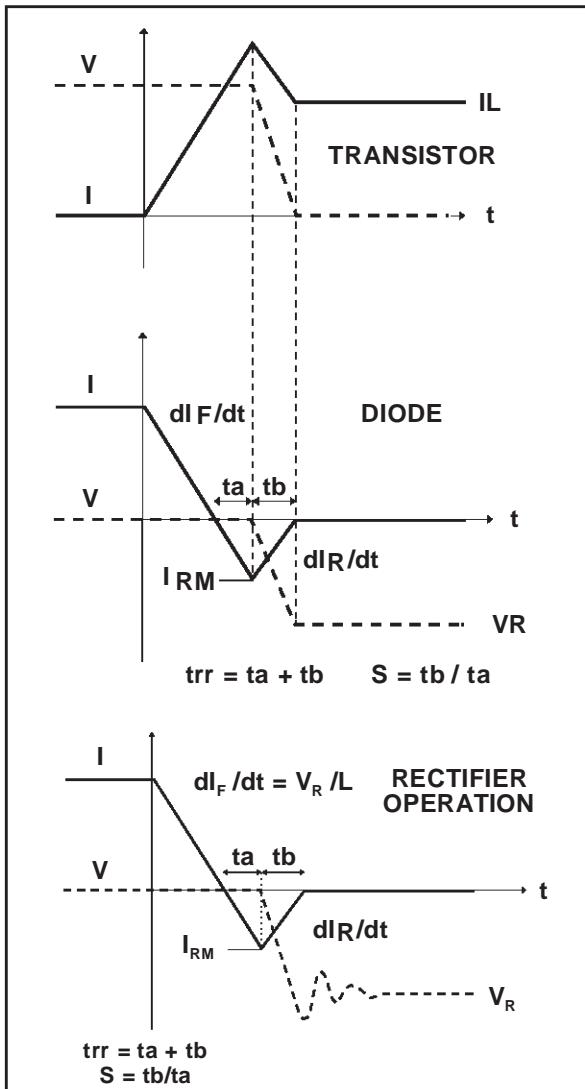
$$P_1 = V_{t0} \cdot I_F(AV) + R_d \cdot I_F^2(RMS)$$

**Reverse losses :**

$$P_2 = V_R \cdot I_R \cdot (1 - \delta)$$

## APPLICATION DATA (Cont'd)

Fig. 7: TURN-OFF CHARACTERISTICS



**Turn-on losses:**  
(in the transistor, due to the diode)

$$P5 = \frac{V_R \times I_{RM}^2 \times (3 + 2 \times S) \times F}{6 \times dI_F/dt} + \frac{V_R \times I_{RM} \times I_L \times (S + 2) \times F}{2 \times dI_F/dt}$$

**Turn-off losses (in the diode):**

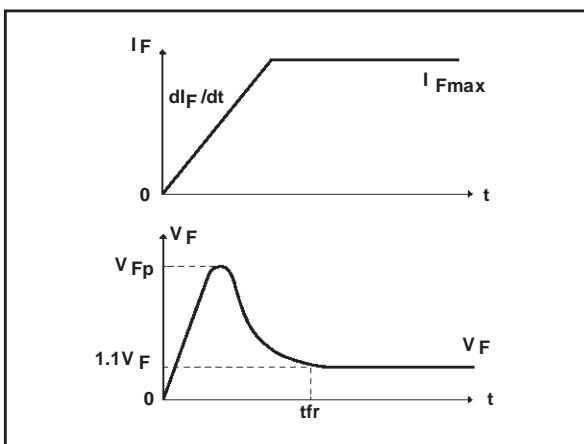
$$P3 = \frac{V_R \times I_{RM}^2 \times S \times F}{6 \times dI_F/dt}$$

**Turn-off losses:**  
(with non negligible serial inductance)

$$P3' = \frac{V_R \times I_{RM}^2 \times S \times F}{6 \times dI_F/dt} + \frac{L \times I_{RM}^2 \times F}{2}$$

P3, P3' and P5 are suitable for power MOSFET and IGBT

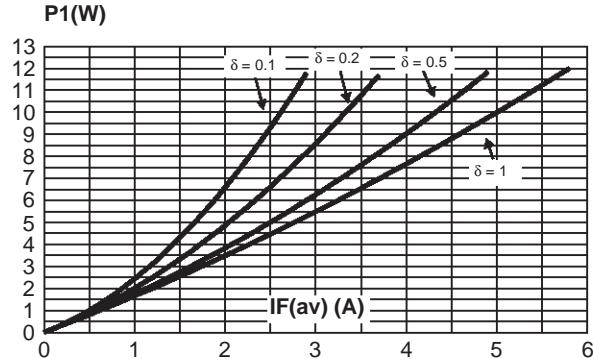
Fig. 8: TURN-ON CHARACTERISTICS



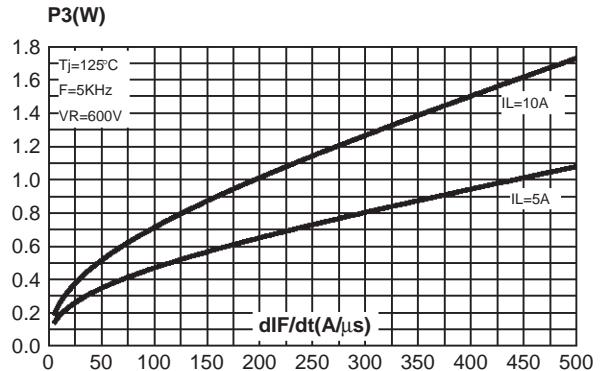
**Turn-on losses:**  
P4 = 0.4 (V<sub>FP</sub> - V<sub>F</sub>) . I<sub>Fmax</sub> . t<sub>f</sub> . F

## STTA512D/F/B

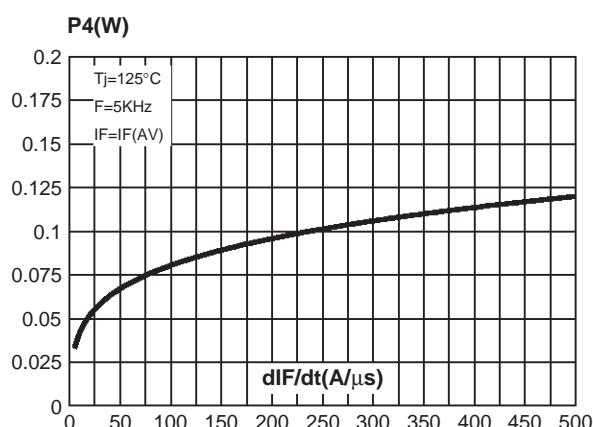
**Fig. 9:** Conductionlosses versus average current.



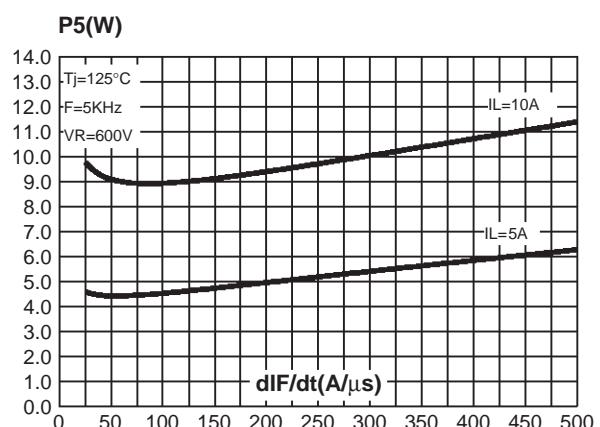
**Fig. 10:** Switching OFF losses versus  $dI_F/dt$ .



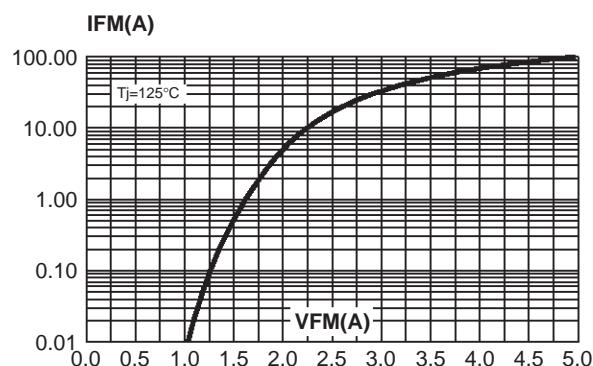
**Fig. 11:** Switching ON losses versus  $dI_F/dt$



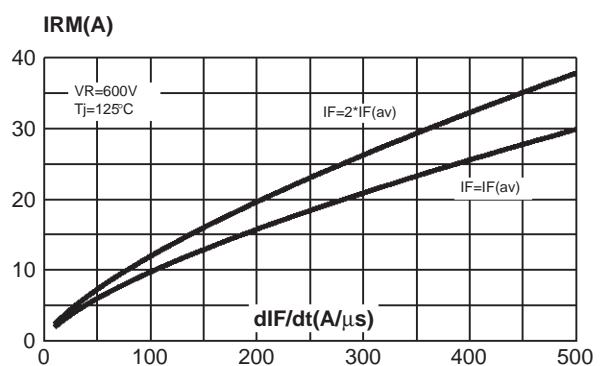
**Fig. 12:** Switching losses in transistor due to the diode.



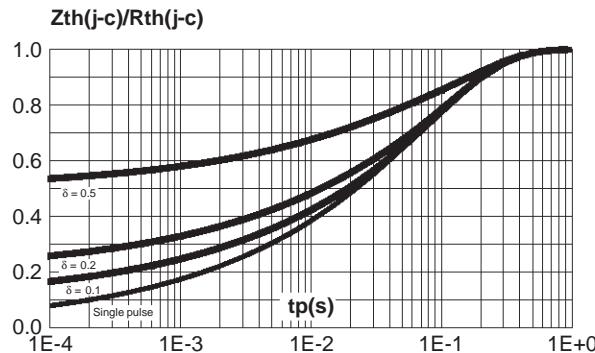
**Fig. 13:** Forward voltage drop versus forward current (maximum values).



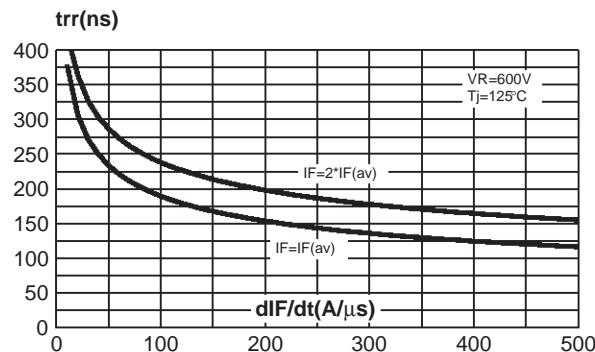
**Fig. 14:** Peak reverse recovery current versus  $dI_F/dt$  (90% confidence).



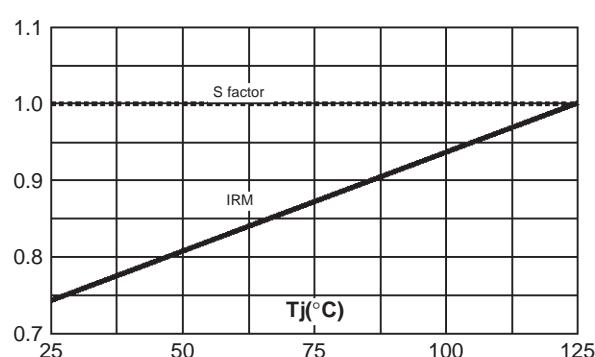
**Fig. 15:** Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC and DPAK).



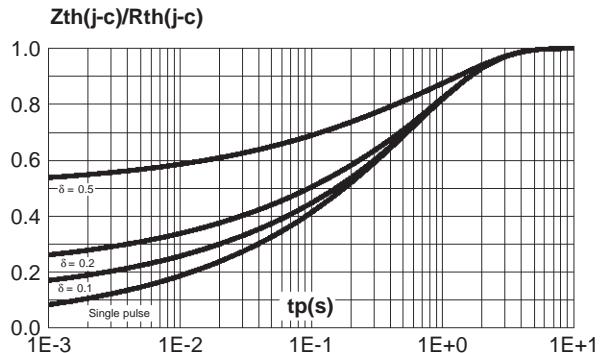
**Fig. 17:** Reverse recovery time versus  $dI_F/dt$  (90% confidence).



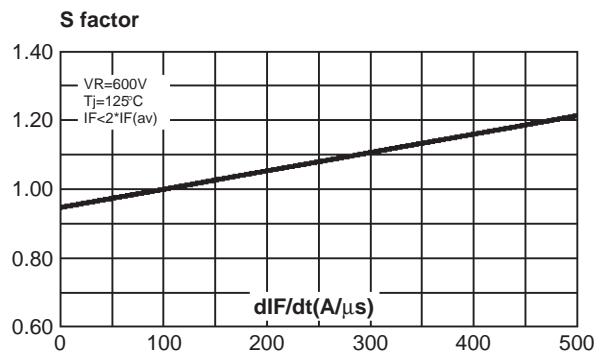
**Fig. 19:** Relative variation of dynamic parameters versus junction temperature (reference  $T_j=125^\circ\text{C}$ ).



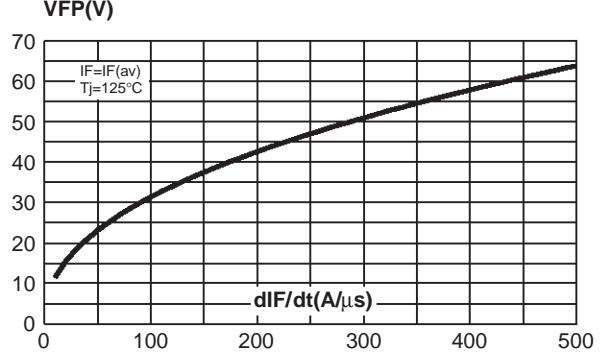
**Fig. 16:** Relative variation of thermal impedance junction to case versus pulse duration (ISOWATT220AC).



**Fig. 18:** Softness factor ( $tb/ta$ ) versus  $dI_F/dt$  (typical values).

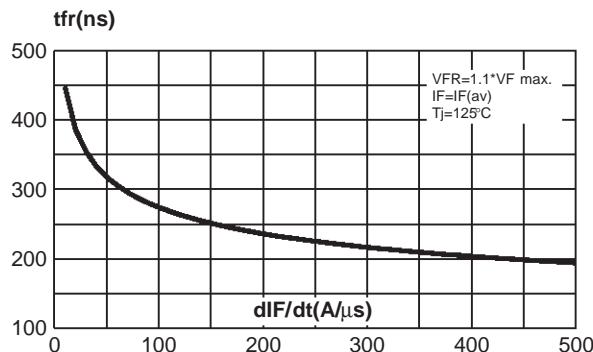


**Fig. 20:** Transient peak forward voltage versus  $dI_F/dt$  (90% confidence).



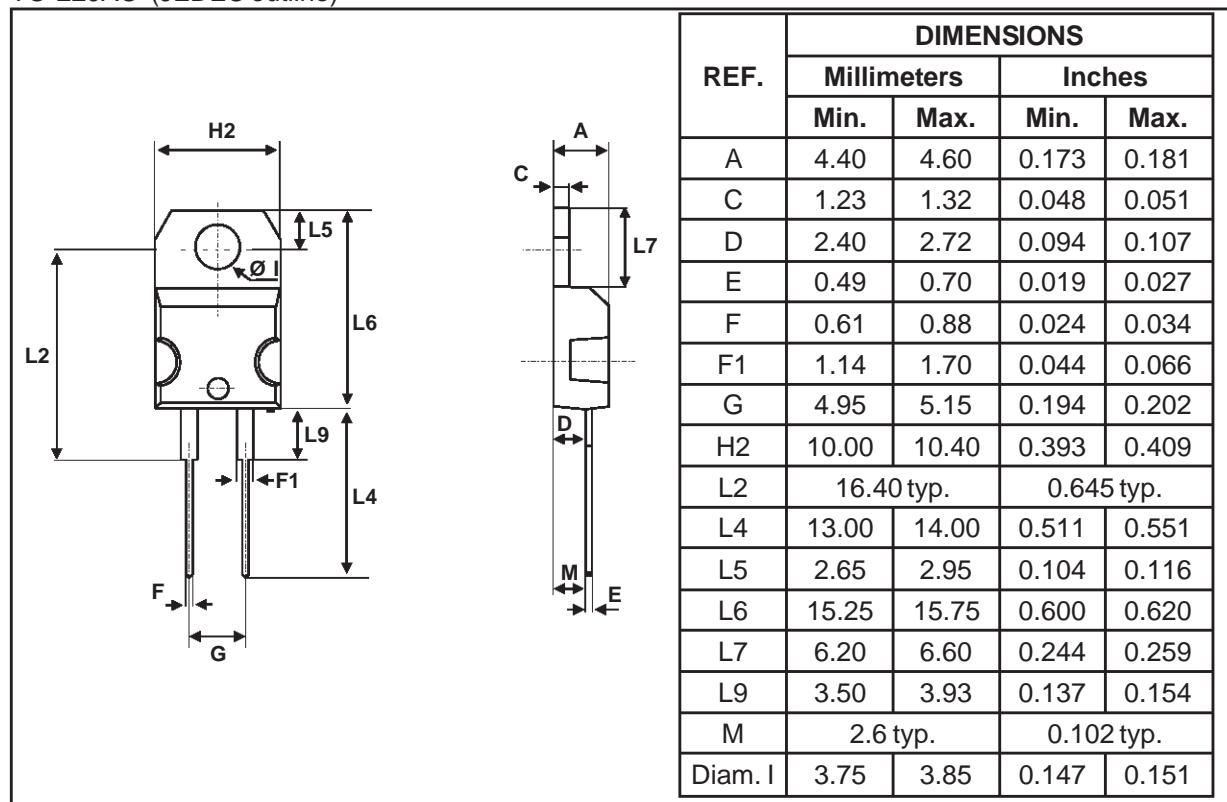
## STTA512D/F/B

**Fig. 21:** Forward recovery time versus  $dI_F/dt$  (90% confidence).



### PACKAGE DATA

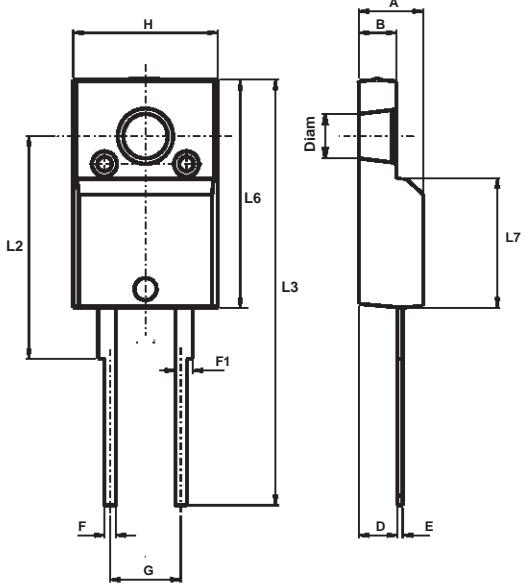
TO-220AC (JEDEC outline)



- **Marking:** Type number.
- **Cooling method:** C.
- **Weight:** 1.9 g.
- **Torque value:** 0.55 m.N typ (0.70 m.N max).

**PACKAGE DATA**  
 ISOWATT220AC

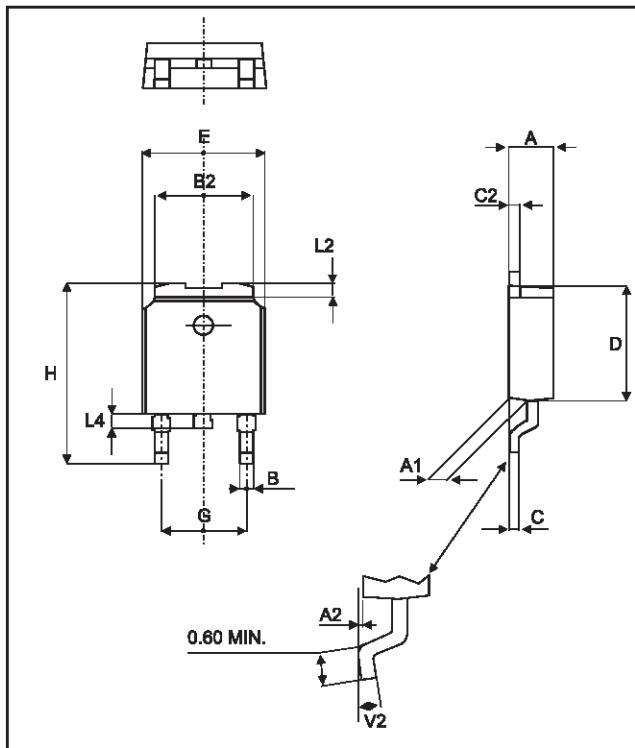
REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	2.50		2.70	0.098		0.106
D	2.40		2.75	0.094		0.108
E	0.40		0.70	0.016		0.028
F	0.75		1.00	0.030		0.039
F1	1.15		1.70	0.045		0.067
G	4.95		5.20	0.195		0.205
H	10.00		10.40	0.394		0.409
L2		16.00			0.630	
L3	28.60		30.60	1.125		1.205
L6	15.90		16.40	0.626		0.646
L7	9.00		9.30	0.354		0.366



- **Marking:** Type number.
- Cooling method: C.
- Weight: 2.0 g.
- Torque value: 0.55 m.N typ (0.70 m.N max).
- Electrical isolation: 2000V DC
- Capacitance: 12 pF

## STTA512D/F/B

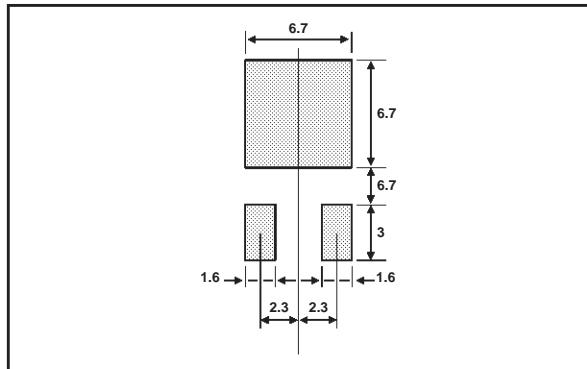
### PACKAGE DATA DPAK



The diagram shows a 3D perspective view of the DPAK package. It features a central rectangular body with a lead frame at the bottom. Lead frame dimensions include A1 (0.60 MIN.), A2 (0.60), C2 (0.48), and L2 (0.80). The top surface has a circular pad. Vertical dimensions include H (9.35), E (6.40), B2 (5.20), and G (4.40). Horizontal dimensions include B (0.64), C (0.45), D (6.00), and L4 (0.60). The lead frame is angled downwards, with a note indicating a minimum angle of 8°.

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.212
C	0.45		0.60	0.017		0.023
C2	0.48		0.60	0.018		0.023
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.251		0.259
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.397
L2		0.80			0.031	
L4	0.60		1.00	0.023		0.039
V2	0°		8°	0°		8°

### FOOTPRINT DIMENSIONS (in millimeters)



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